

**Date:** February 2021  
**Rev:** VI  
**No. of Components:** Two  
**Mix Ratio by Weight:** 1 : 1  
**Specific Gravity:** Part A: 1.12      Part B: 0.94  
**Pot Life:** 1 Hour  
**Shelf Life- Bulk:** One year at room temperature

**Recommended Cure: 80°C / 2 Hours**

Minimum Alternative Cure(s):  
*May not achieve performance properties listed below*  
 100°C / 30 Minutes  
 23°C / 24 Hours

**NOTES:**

- Container(s) should be kept closed when not in use.
- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.
- Syringe packaging will impact initial viscosity and effective pot life, potentially beyond stated parameters.

**Product Description:** EPO-TEK® 730 is a two component, thixotropic, room temperature-curing epoxy adhesive.

**Typical Properties:** Cure condition: 80°C / 2 Hours      Different batches, conditions & applications yield differing results.  
 Data below is not guaranteed. To be used as a guide only, not as a specification. \* denotes test on lot acceptance basis

PHYSICAL PROPERTIES:			
* Color (before cure):	Part A: Tan	Part B: Tan	
* Consistency:	Smooth paste		
* Viscosity (23°C) @ 2.5 rpm:	80,000-120,000	cPs	
Thixotropic Index:	2.1		
* Glass Transition Temp:	≥ 55 °C (Dynamic Cure: 20-200°C/ISO 25 Min; Ramp -10-200°C @20°C/Min)		
Coefficient of Thermal Expansion (CTE):			
	Below Tg:	66	x 10 <sup>-6</sup> in/in°C
	Above Tg:	248	x 10 <sup>-6</sup> in/in°C
Shore D Hardness:	64		
Lap Shear @ 23°C:	> 2,000	psi	
Die Shear @ 23°C:	≥ 10	Kg	3,556 psi
Degradation Temp:	364 °C		
Weight Loss:			
	@ 200°C:	1.41	%
	@ 250°C:	2.22	%
	@ 300°C:	4.16	%
Suggested Operating Temperature:	< 250 °C (Intermittent)		
Storage Modulus:	123,527	psi	
* Particle Size:	≤ 20	microns	

ELECTRICAL AND THERMAL PROPERTIES:			
Thermal Conductivity:	N/A		
Volume Resistivity @ 23°C:	≥ 3 x 10 <sup>13</sup>	Ohm-cm	
Dielectric Constant (1KHz):	3.17		
Dissipation Factor (1KHz):	0.021		

**Epoxyes and Adhesives for Demanding Applications™**

**This information is based on data and tests believed to be accurate. Epoxy Technology, Inc. makes no warranties (expressed or implied) as to its accuracy and assumes no liability in connection with any use of this product.**

EPOXY TECHNOLOGY, INC.  
 14 FORTUNE DRIVE, BILLERICA, MA 01821 (978) 667-3805, FAX (978) 663-9782  
[www.epotek.com](http://www.epotek.com)

**EPO-TEK® 730 Advantages & Suggested Application Notes:**

- Excellent “all-purpose adhesive”. Many uses in job shop and repair businesses, home or household, outdoor, recreation, camping, automotive, boating; and industrial use such as filtration and metal working.
- Designed for those applications where a limited amount of flow is desirable. Capillary forces do not pull the epoxy out of alignment.
- The paste-like appearance allows it to be spread by hand using a spatula or blade, by dispensing equipment, or specialty packaging.
- The 1:1 mix ratio allows it to be easily mixed by volume or by weight.
- Used in the fabrication of X-ray sensors. Adheres to metal foils and substrates, especially lead.
- Available in black and in different viscosities. Contact [techserv@epotek.com](mailto:techserv@epotek.com) for your best recommendation.
- Excellent adhesion to foam/plastics; especially those used in filtration applications.
- Suggested for LCD plug-seal or end-seal, due to its high viscosity nature and room temperature cure.
- Can be used for joining SMDs to PCB, for staking applications, or double sided PCB. It has wet, “green strength” before cure. In many cases, the thixotropic nature of the adhesive will hold parts in place without special fixtures while the hardening process is taking place.
- Very popular epoxy for wood-working applications.
- Versatility in curing options between 23°C and 100°C.

**Epoxyes and Adhesives for Demanding Applications™**

**This information is based on data and tests believed to be accurate. Epoxy Technology, Inc. makes no warranties (expressed or implied) as to its accuracy and assumes no liability in connection with any use of this product.**

EPOXY TECHNOLOGY, INC.

14 FORTUNE DRIVE, BILLERICA, MA 01821 (978) 667-3805, FAX (978) 663-9782

[www.epotek.com](http://www.epotek.com)